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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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1025HC

Fast-acting, high current, surface mount ceramic tube fuses



Product description

- · Fast-acting high current fuse
- · Compact design utilizes less board space
- 20 A to 50 A current ratings
- Ceramic tube, silver plated brass end cap construction
- Halogen free and RoHS compliant

Applications

Primary and secondary circuit protection:

- · Server and desktop power supplies
- · Gaming console systems
- Voltage Regulator Module (VRM)
- · Storage system power
- · Base station power supplies
- · Basic power supplies
- · LED and general lighting
- · Test equipment

Agency information

- cURus Recognition file number: E19180, Guide JDYX2/JDYX8
- PSE: JET 7042-31007-1002 (20 A to 30 A)

Ordering

• Use ordering number (see page 7 for details)

Packaging suffixes

 -TR (20 A to 30 A: 1500 parts per 13" diameter reel, tape width 24 mm) (40 A to 50 A: 1000 parts per 13" diameter reel, tape width 24 mm)



Electrical characteristics

% of Amp Rating	Opening Time	
100	4 hours minimum	
200	60 s maximum	

Product specifications

Part number ⁴	Current rating (A)	Voltage rating (V _{AC})	Voltage rating (V _{DC})	Interrupting rating at rated voltage (A _{AC})	Interrupting rating at rated voltage ¹ (A _{DC})	Typical DC cold resistance 2 ($m\Omega$)	Typical melting³ I²t (A²s)	Part marking	cURus	PSE
1025HC20-R	20	250	72	100	500	3.1	25	<ps> E JET BUSS 20A</ps>	Х	Х
1025HC25-R	25	250	72	100	500	2.6	50	<ps> E JET BUSS 25A</ps>	Х	Х
1025HC30-R	30	250	72	100	500	1.7	112	<ps> E JET BUSS 30A</ps>	Х	Х
1025HC40-R	40	250	72	100	500	1.3	400	BUSS 40A	Х	
1025HC50-R	50	NA	60	NA	600	1.1	600	BUSS 50A	Х	

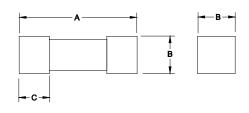
¹ DC interrupting rating measured at rated voltage, time constant of less than 1.0 microseconds, battery source

1025HC= Product code and size

xx= Ampere rating

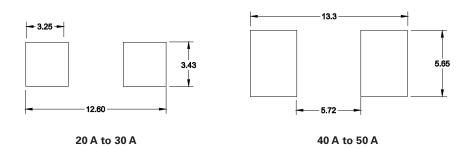
-R= Rohs compliant

Dimensions (mm)



Rating	Α	В	С
20 A to 30 A	10.0 ±0.50	3.15 ±0.15	1.70 ±0.15
40 A to 50 A	12.4 ±0.50	4.50 ±0.15	2.70 ±0.15

Recommended pad layout (mm)



Recommended trace thickness is 3 oz.

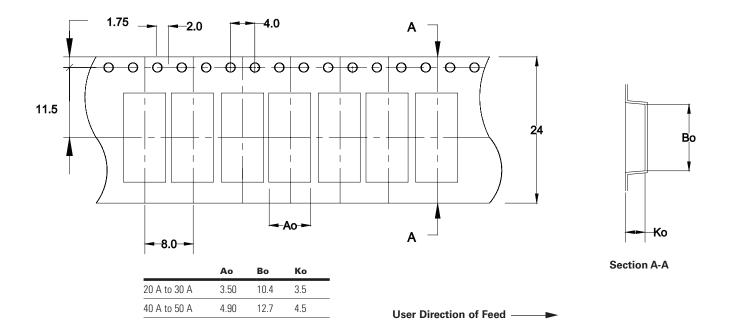
Recommended min-trace width is 10 mm (20 A to 30 A) and 15 mm (40 A to 50 A)

² Typical DC cold resistance measured at <10% of rated current at an ambient temperature of 20 °C (reference only)

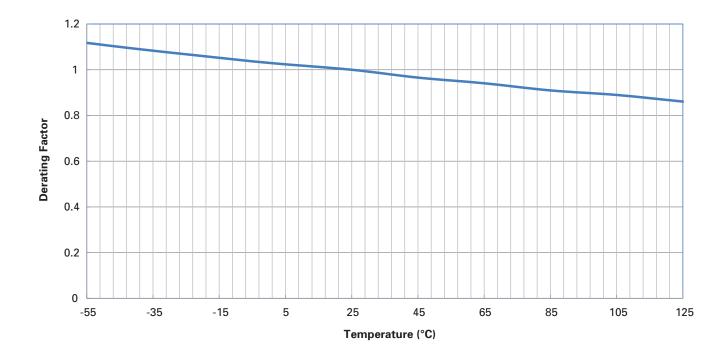
^{3.} Typical melting I2t value is measured at 10ln rated current

^{4.} Part number definition: 1025HCxx-R

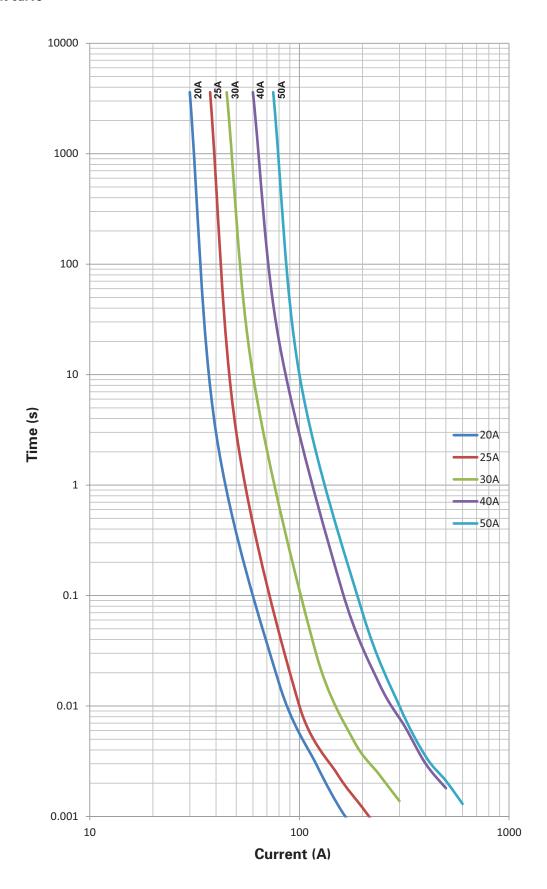
Packaging information (mm)



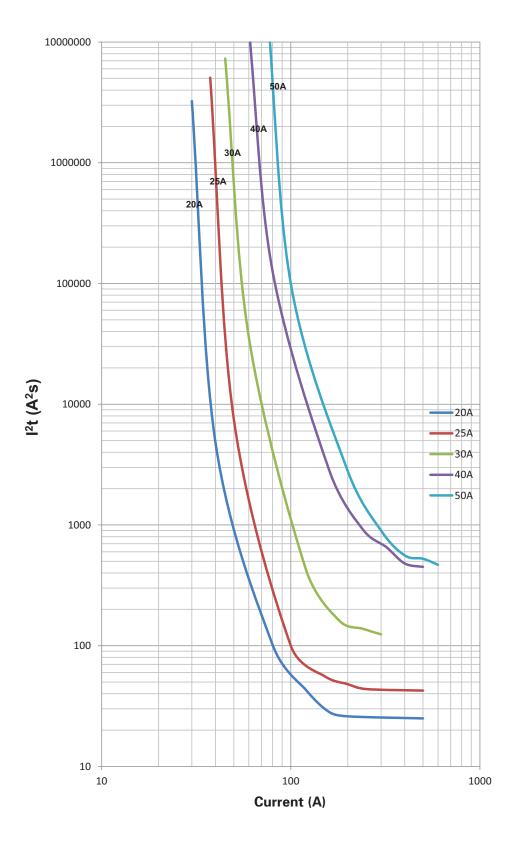
Temperature derating curve



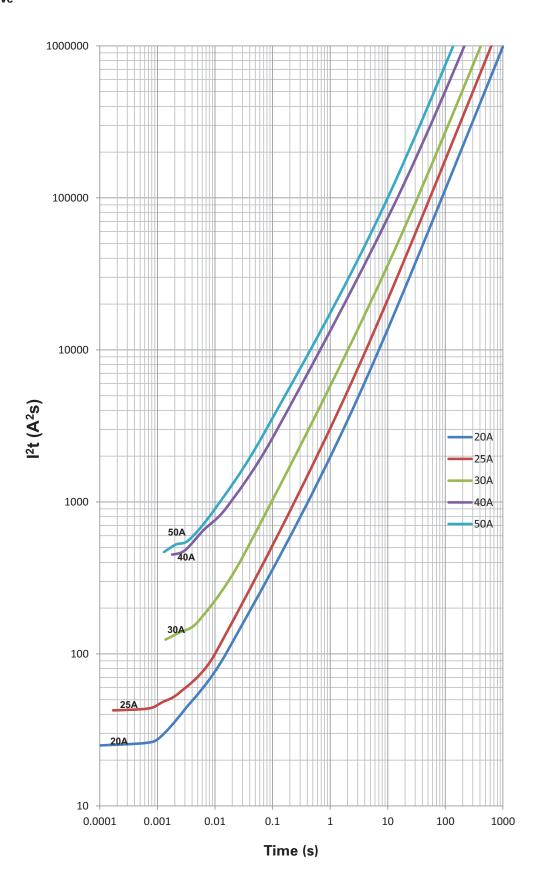
Time vs. current curve



l²t vs. current curve



I2t vs. time curve



Environmental data

Operating temperature: - 55 °C to 125 °C (with derating)
Thermal cycling: (100 cycles - 55 °C to 125 °C)
Vibration: (20 g's, 10 Hz - 2000 Hz)
Board flex: 60 s, 2 mm
Mechanical shock: 3000 g, 0.3 ms
Termination strength: 1.8 kg, 60 s
Solderability test: J-STD- 002, Method B1, G1 and D

Ordering codes

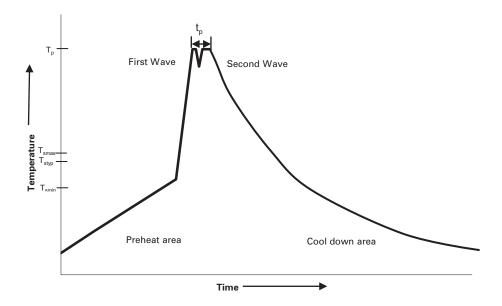
The ordering code is the part number adding the packaging suffix.

	Ordering codes	
Part number	-TR option	
1025HC20-R	1025HC20-RTR	
1025HC25-R	1025HC25-RTR	
1025HC30-R	1025HC30-RTR	
1025HC40-R	1025HC40-RTR	
1025HC50-R	1025HC50-RTR	

Packaging suffixes

• -TR (20 A to 30 A: 1500 parts per 13" diameter reel, tape width 24 mm) (40 A to 50 A: 1000 parts per 13" diameter reel, tape width 24 mm)

Wave solder profile



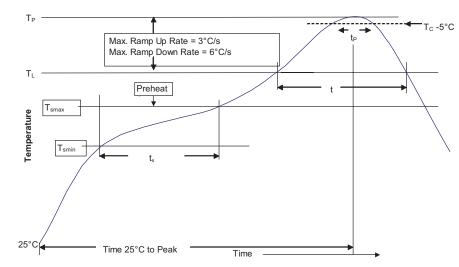
Reference EN 61760-1:2006

Profile Feat	ture	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat	• Temperature min. (T _{smin})	100 °C	100 °C
	• Temperature typ. (T _{styp})	120 °C	120 °C
	• Temperature max. (T _{smax})	130 °C	130 °C
	• Time (T _{Smin} to T _{Smax}) (t _S)	70 seconds	70 seconds
Δ preheat to	max Temperature	150 °C max.	150 °C max.
Peak tempera	ature (T _P)*	235 °C − 260 °C	250 °C − 260 °C
Time at peak	temperature (t _p)	10 seconds max 5 seconds max each wave	10 seconds max 5 seconds max each wave
Ramp-down r	rate	~ 2 K/s min ~3.5 K/s typ ~5 K/s max	~ 2 K/s min ~3.5 K/s typ ~5 K/s max
Time 25 °C to	25 °C	4 minutes	4 minutes

Manual solder

350 °C, 4-5 seconds (by soldering iron), generally manual, hand soldering is not recommended.

Solder reflow profile



-_{Tc-5°C} Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5mm)	235 °C	220 °C
≥2.5mm	220 °C	220 °C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm³ <350	Volume mm³ 350 - 2000	Volume mm³ >2000
<1.6mm	260 °C	260 °C	260 °C
1.6 – 2.5mm	260 °C	250 °C	245 °C
>2.5mm	250 °C	245 °C	245 °C

Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak • Temperature min. (T _{smin})	100 °C	150 °C
• Temperature max. (T _{smax})	150 °C	200 °C
• Time (T _{smin} to T _{smax}) (t _s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T_{smax} to T_{p}	3 °C/ Second Max.	3 °C/ Second Max.
Liquidous temperature (TL) Time at liquidous (tL)	183 °C 60-150 Seconds	217 °C 60-150 Seconds
Peak package body temperature (Tp)*	Table 1	Table 2
Time $(t_p)^{**}$ within 5 °C of the specified classification temperature (T_c)	20 Seconds**	30 Seconds**
Average ramp-down rate (T _p to T _{Smax})	6 °C/ Second Max.	6 °C/ Second Max.
Time 25 °C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

 $^{^{*}}$ Tolerance for peak profile temperature (T $_{\rm p}$) is defined as a supplier minimum and a user maximum.

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^{**} Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.